

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A cleaning device comprising:
a pure water supply;
first and second injectors that eject pure water supplied from the pure water supply onto a wafer;
first and second nozzles attached to ends of the respective first and second injectors;
a brush that cleans the wafer during a linear horizontal movement between a center and edges of the wafer; and
a brush arm that supports and moves the brush,
wherein the first injector is in a fixed position so as not to move together with the brush arm, and ejects the pure water at an upper position of the wafer toward the center of the wafer, and
wherein the second injector is disposed adjacent to the brush along one side of the brush arm so as to move together with the brush arm, and supplies the pure water toward the wafer.
2. (Previously presented) The cleaning device as recited in claim 1, wherein the second nozzle is disposed such that it is perpendicular to a top surface of the wafer that is in contact with the brush.
3. (Original) The cleaning device as recited in claim 1, wherein the first injector is arranged to be perpendicular to the second injector.

4. (Original) The cleaning device as recited in claim 3, wherein the brush arm moves in a direction parallel to linear orientation of the first injector.

5. (Previously presented) The cleaning device as recited in claim 1, wherein the brush arm is movable in a vertical direction to keep the brush a desired distance from a surface of the wafer.

6. (Previously presented) The cleaning device as recited in claim 1, wherein the brush arm is movable in a vertical direction to keep the brush in contact with a surface of the wafer.

7. (Previously presented) The cleaning device as recited in claim 1, wherein the brush moves perpendicularly with respect to a direction along which the first injector extends.

8. (Original) A cleaning device comprising:
a pure water supply;
first injector that ejects pure water supplied from the pure water supply onto a central portion of the wafer;
a plurality of second injectors that eject pure water supplied from the pure water supply onto the wafer;
a first nozzle attached to the first injector;
a plurality of second nozzles respectively attached to the second injectors;
a brush that cleans the wafer during horizontal movement between a center and edges of the wafer, while the pure water is ejected by the first and second nozzles; and
a brush arm that supports and moves the brush,

wherein the plurality of second injectors comprise a plurality of pipe lines formed along a circumference of the brush arm, the end of the pipelines facing a top surface of the wafer.

9. (Original) The cleaning device as recited in claim 8, wherein the plurality of second injectors are tightly fixed to the brush arm by a fixing apparatus.

10. (Original) The cleaning device as recited in claim 8, wherein the first injector is arranged to be perpendicular to the plurality of second injectors.

11. (Original) The cleaning device as recited in claim 10, wherein the brush arm moves in a direction parallel to a linear orientation of the first injector.

12. (Previously presented) The cleaning device as recited in claim 8, wherein the brush arm is movable in a vertical direction to keep the brush a desired distance from a surface of the wafer.

13. (Previously presented) The cleaning device as recited in claim 8, wherein the brush arm is movable in a vertical direction to keep the brush in contact with a surface of the wafer.

14. (Previously presented) The cleaning device of claim 1, where the first injector extends along a radial direction from an edge of the wafer toward the center of the wafer, and ejects the pure water onto a central portion of the wafer.

15. (Previously presented) The cleaning device of claim 8, where the first injector extends along a radial direction from an edge of the wafer toward the center of the wafer, and ejects the pure water onto a central portion of the wafer.